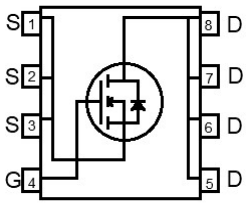
• General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. It is suitable for automotive application.

• Product Summary



V_{DS}= 80V
$R_{DS(ON)}$ = 2.35mΩ
I_D= 127A

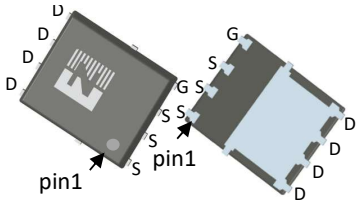
• Features

■AEC-Q101 Qualified

■Low $R_{DS(ON)}$ to minimize conductive loss

■Low Gate Charge for fast switching

■Low Thermal resistance



DFN5*6

•Application

■BLDC Motor driver

■DC-DC

■Load Switch

•Ordering Information:

Part NO.	ZMSA028N08HNC
Marking	ZMS028N08H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

•Absolute Maximum Ratings (T_C=25℃)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		80	V
Gate-Source Voltage①	V_{GS}		±20	V
Continuous Drain Current	I_D	T_C=25℃	127	A
	I_D	T_C=75℃	111	A
	I_D	T_C=100℃	92	A
Pulsed Drain Current	I_{DM}	Pulsed; t_p ≤ 10 μs; T_{mb} = 25 °C;	508	A
Total Power Dissipation	P_D	T_C=25℃	115	W
Total Power Dissipation	P_D	T_A=25℃	3.3	W
Operating Junction Temperature	T_J		-55 to +175	℃
Storage Temperature	T_{STG}		-55 to +175	℃
Single Pulse Avalanche Energy	E_{AS}	L=0.1mH, V_{GS}=10V, Rg=25Ω,	240	mJ
		L=0.5mH, V_{GS}=10V, Rg=25Ω,	396	mJ
ESD Level (HBM)	CLASS 2			

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	1.3	°C/W
Thermal resistance, junction-ambient	R_{thJA} ②		-	45	°C/W
Soldering temperature	Tsold		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} =0V, I_D =250uA	80			V
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} =V_{DS}, I_D =250uA	2.0	2.7	4.0	V
Drain-Source Leakage Current	I_{DSS}	V_{GS}=0V, V_{DS}= 80V			1.0	uA
Gate- Source Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS} = 0V			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D= 30A		2.35	3	mΩ
Forward Transconductance	g_{FS}	V_{DS} =5V, I_{SD} = 10A		28		s
Diode Forward Voltage	V_{FSD}	V_{GS} =0V, I_{SD} = 30A		0.83	1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	Ciss	f = 1MHz, V_{DS}=40V	-	4313	-	pF
Output capacitance	Coss		-	948	-	
Reverse transfer capacitance	Crss		-	46	-	
Gate Risistance	Rg	f = 1MHz	-	1.8		Ω
Total gate charge	Qg	V_{DD} = 15V, I_D = 30A, V_{GS} = 10V	-	61	-	nC
Gate - Source charge	Qgs		-	9.7	-	
Gate - Drain charge	Qgd		-	19	-	
Turn-ON Delay time	$t_{D(on)}$	V_{GS}=10V,V_{DS}=15V, R_G =3.3Ω, I_D =30A	-	14	-	ns
Turn-ON Rise time	t_r		-	9	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	26	-	ns
Turn-Off Fall time	t_f		-	18	-	ns
Reverse Recovery Time	t_{RR}	V_{DD}=20V, dI_S/dt = 100A/us, I_S=50A	-	60	-	ns
Reverse Recovery Charge	Q_{RR}		-	97	-	nC

Fig.1 Gate-Charge Characteristics

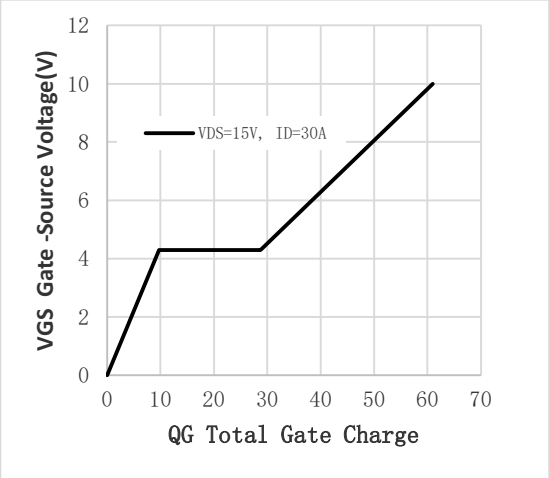


Fig.2 Capacitance Characteristics

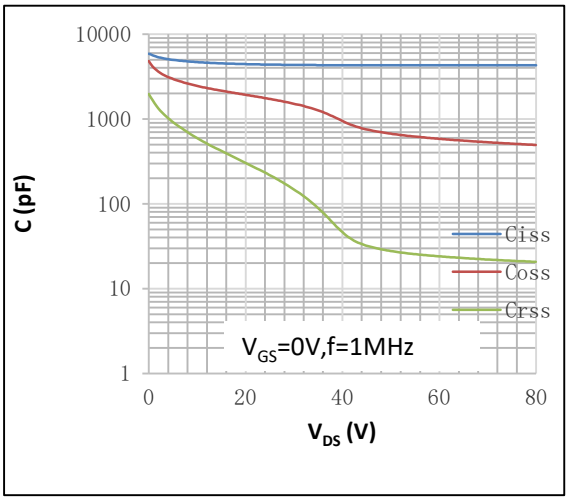


Fig.3 Power Dissipation

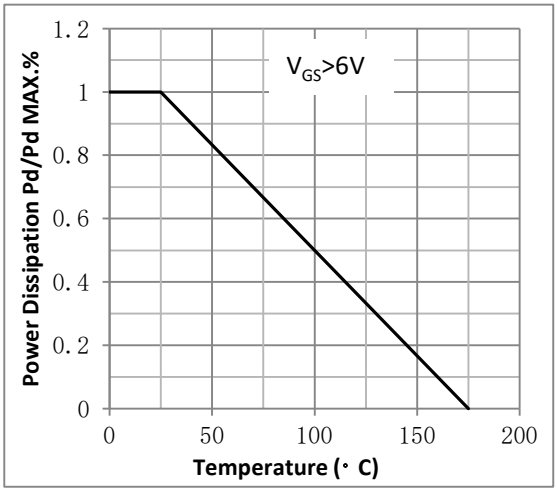


Fig.4 Typical output Characteristics

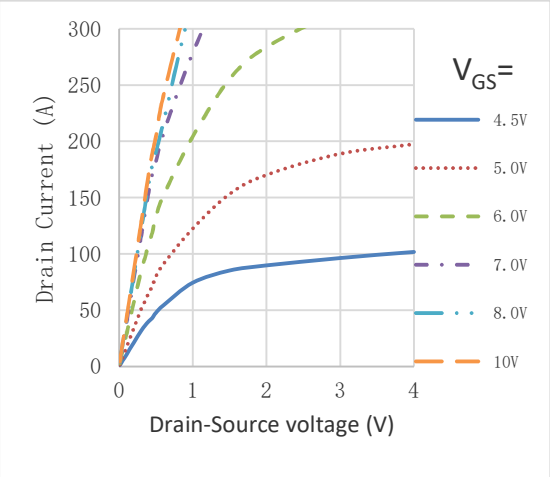


Fig.5 Threshold Voltage V.S Junction Temperature

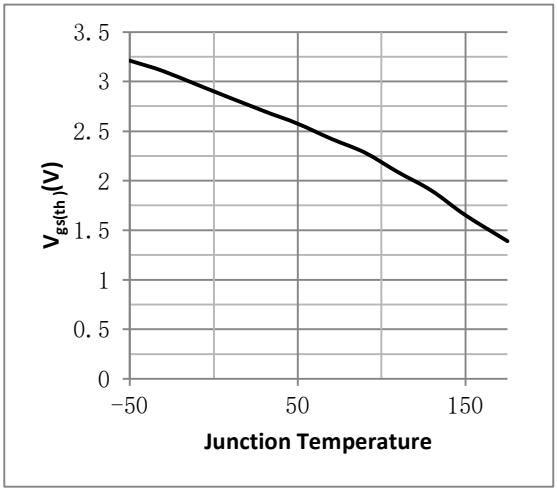


Fig.6 Resistance V.S Drain Current

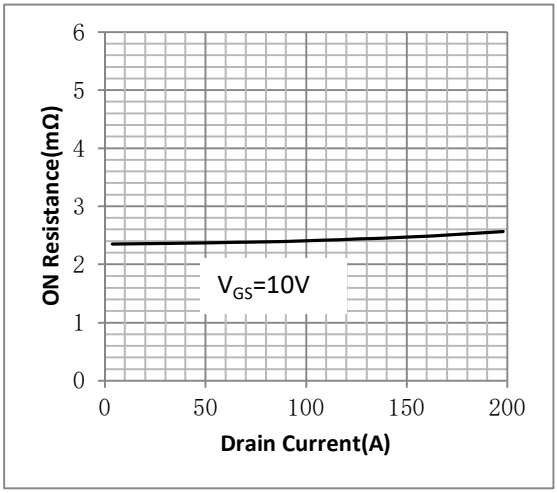


Fig.7 On-Resistance VS Gate Source Voltage

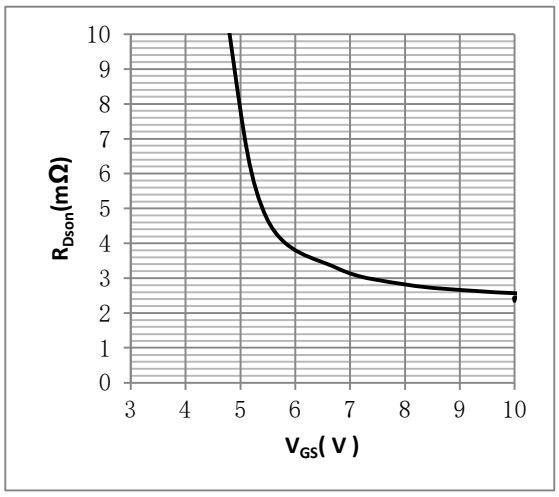


Fig.8 On-Resistance V.S Junction Temperature

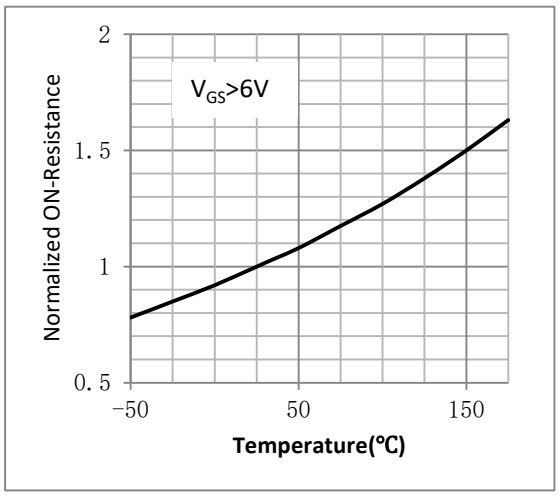


Figure 9. Diode Forward Voltage vs. Current

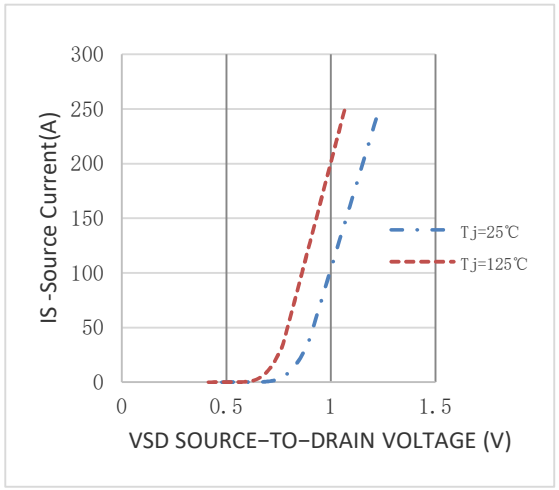


Figure 10. Transfer Characteristics

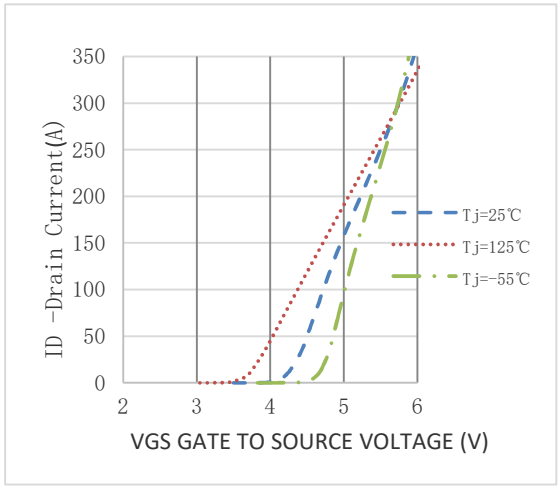


Fig.11 Safe Operating Area

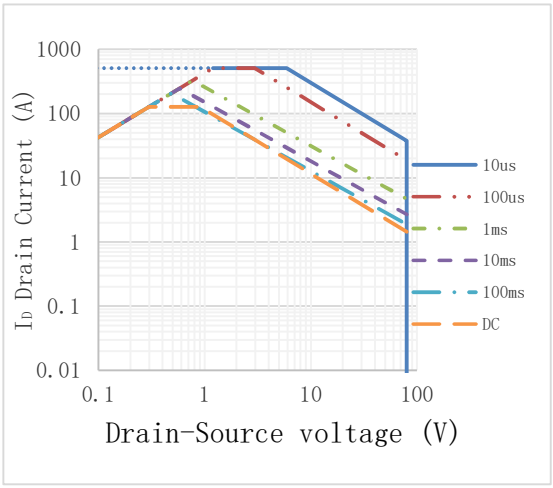
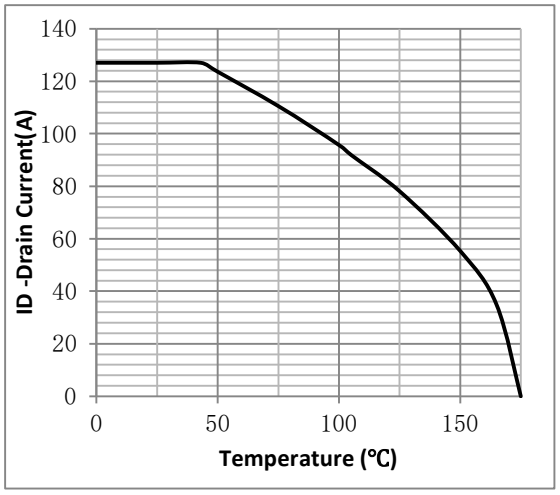
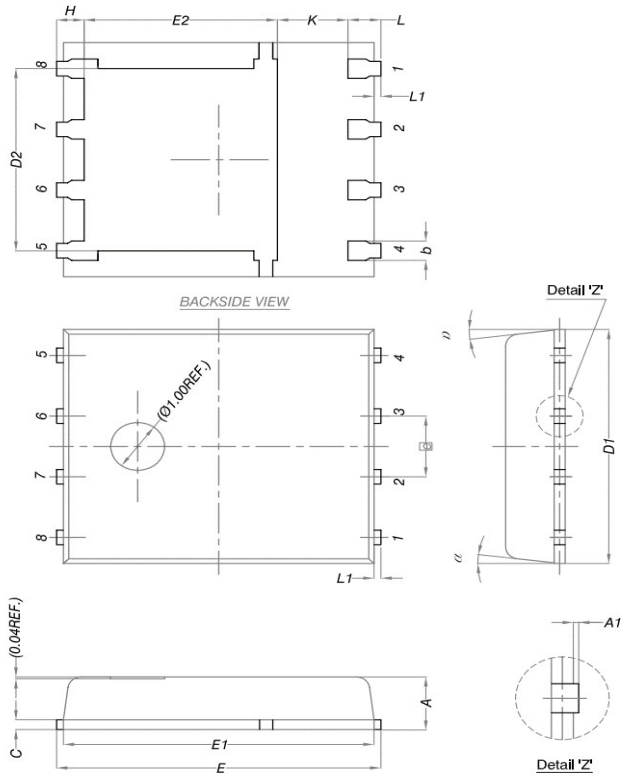


Fig.12 ID vs. Junction Temperature③



●DFN5*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°

Note:

① Pulse : VGS=+20V/-20V, Duty cycle=50%,Tj=175℃, t=1000 hours; For DC， the following test conditions can be passed: VGS=+20V/-10V, Tj=175℃, t=1000 hours；

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate；

③Practically the current will be limited by PCB, thermal design and operating temperature. V_{GS}=10V.

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Revision History

Version	Date	Change
A	2023.12.15	New
B	2024.5.14	Correct ciss
C	2024.11.6	RDSon modified.
D	2025.7.1	1. Update Cg condition and curve. 2. Add VFSD typical value.